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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Papathomas *et al.*

Examiner: Berman, S

Serial No.: 09/771,275

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For: **LEAD PROTECTIVE COATING COMPOSITION, PROCESS AND  
STRUCTURE THEREOF**

Commissioner for Patents  
Washington D.C. 20231

RECEIVED  
APR 05 2002  
TC 1700

PRELIMINARY AMENDMENT

Sir:

Prior to initial examination on the merits, please amend the above-identified application  
as follows:

IN THE CLAIMS

Please amend claims 13, 15 and 20.

Sub D1  
13. (TWICE AMENDED) A method for encapsulating a solder joint between an integrated  
circuit chip and a substrate, comprising the steps of:

forming a composition that includes a cyanate ester, a photoinitiator, and a coefficient  
of thermal expansion reducing dispersed filler;

applying an amount of the composition at a thickness sufficient to cover substantially all  
of the solder joint; and

photocuring the composition to reinforce the solder joint.